

**IN THE CLAIMS:**

Please note that, pursuant to 37 CFR 1.121(c)(3), all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity and for the convenience of the Patent Office.

Please amend claims 19, 21 through 23, 25 through 32 and 34, as set forth below.

*C1*  
19. (Twice Amended) A method of fabricating a multi-die assembly, comprising:  
providing a substrate including a plurality of conductors;  
attaching at least one active face-down base die to said substrate in electrical communication with at least some of said plurality of conductors;  
securing the back side of at least one active face-up stack die to said at least one base die with electrically conductive adhesive;  
electrically connecting said at least one stack die to at least one of said conductors; and  
electrically grounding said at least one base die via said electrically conductive adhesive and said at least one stack die.

*C2 (auto)*  
21. (Twice Amended) The method of claim 19, further comprising:  
securing at least one discrete component to at least one of said at least one stack die, said at least one base die, and said substrate;  
electrically connecting said at least one discrete component to at least one of said stack die, said base die, and said substrate  
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

22. (Twice Amended) The method of claim 19, further comprising:

extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

C2 23. (Twice Amended) The method of claim 19, further comprising:  
securing at least another stack die to said assembly; and  
electrically connecting said at least another stack die and at least one of said plurality of substrate conductors.

25. (Amended) The method of claim 23, further comprising securing said at least another stack die to said at least one stack die.

C3 26. (Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one stack die; and  
extending a die-to-component bond wire between said at least another stack die and said at least one discrete component.

27. (Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one stack die; and  
extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

28. (Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one base die; and  
extending a die-to-component bond wire between said at least another stack die and said at least one discrete component.

29. (Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one base die; and

extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

30. (Twice Amended) The method of claim 19, wherein the attaching ate least one active face-down base die includes attaching at least two active face-down base die to said substrate and electrically coupling each of said at least two base die with at least one of said plurality of substrate conductors.

31. (Amended) The method of claim 30, further comprising bridging said at least one stack die between said at least two base die.

32. (Amended) The method of claim 31, further comprising securing at least another stack die over said at least one stack die.

33. (Previously Amended) The method of claim 19, further comprising:  
securing at least one discrete component to said substrate; and  
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

34. (Twice Amended) The method of claim 31, further comprising:  
securing at least another discrete component to said substrate; and  
extending a die-to-component bond wire between said at least one stack die and said at least another discrete component.